

Update: 12/10/2016	TECHNICAL DATA SHEET	
Ref: Alloy	LEAD FREE Alloy	
Created on: 20/02/03	Sn96.5Ag3.5	



GENERAL CHARACTERISTICS:

Eutectic alloy for soldering printed circuits, produced from very high quality metals.
Conform to standard ISO 9453 : alloy n° 703.

CHEMICAL CHARACTERISTICS:

Amount of Tin : 96.5 % ± 0.5%
Amount of Copper : 3.5 % ± 0.2%
Material global purity : **99.95%**

PHYSICAL CHARACTERISTICS:

Melting point : Eutectic 221°C
Specific weight : 7.3 g/cm³
Working temp. : 300°C to 450 °C

PACKAGING / STORAGE:

Bars : Extruded Bars or Sticks in cartons of 20kg (exact tare weight stated).
Solder wire : Various types of reels available adapted to Customer's needs.
Depending on diameter and length.
Other product shape : On request
Storage : In original packaging at room temperature for 12 months.

SAFETY:

Material Safety Data Sheet available on request. Please consult it before use.

ADDITIONAL INFORMATION:

Our manufacturing processes have been subjected to FMECA analysis (equivalent of AMDEC in Europe).
Quality Certificate available on request.



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